

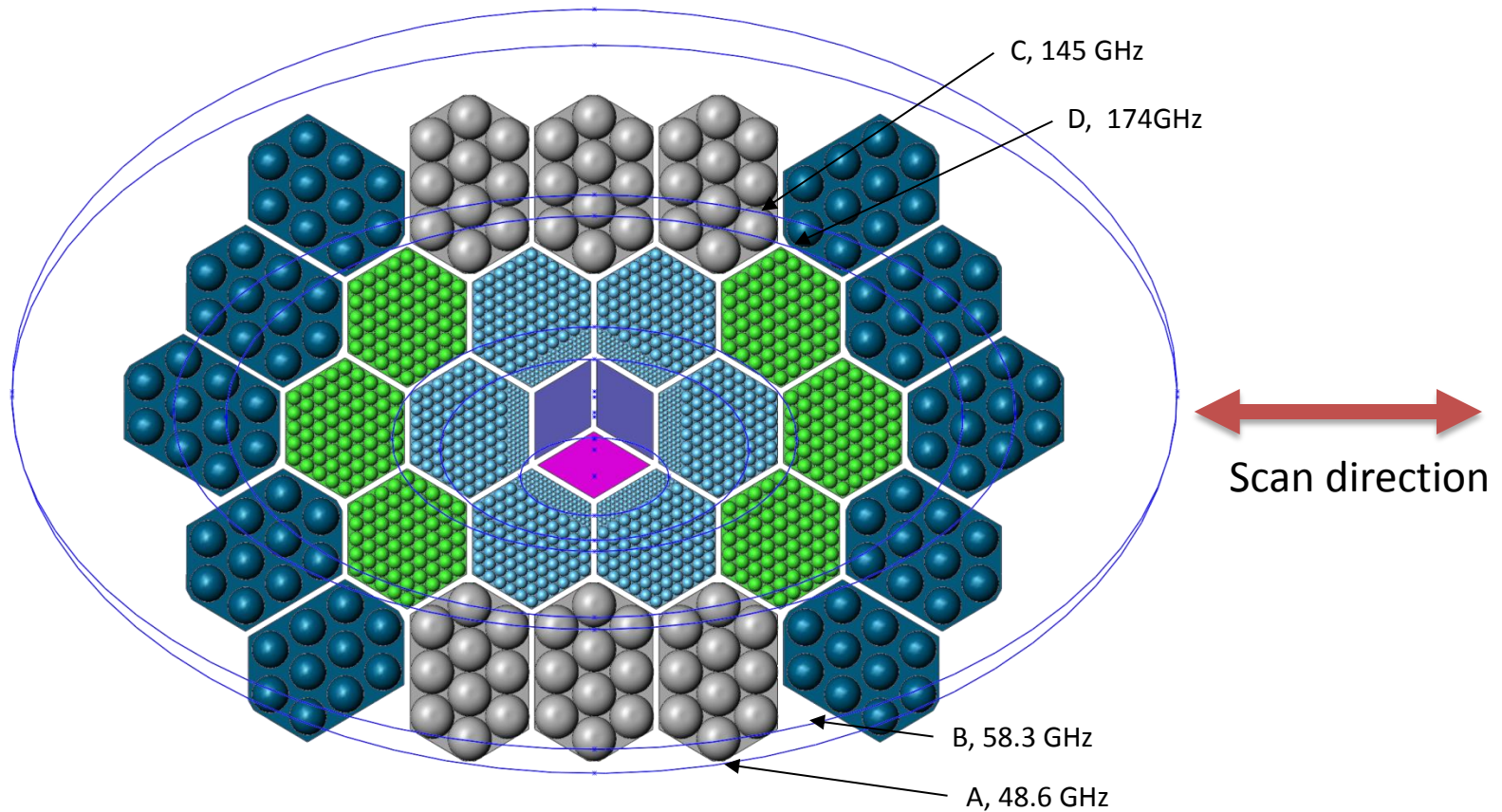
# Focal Plane Status

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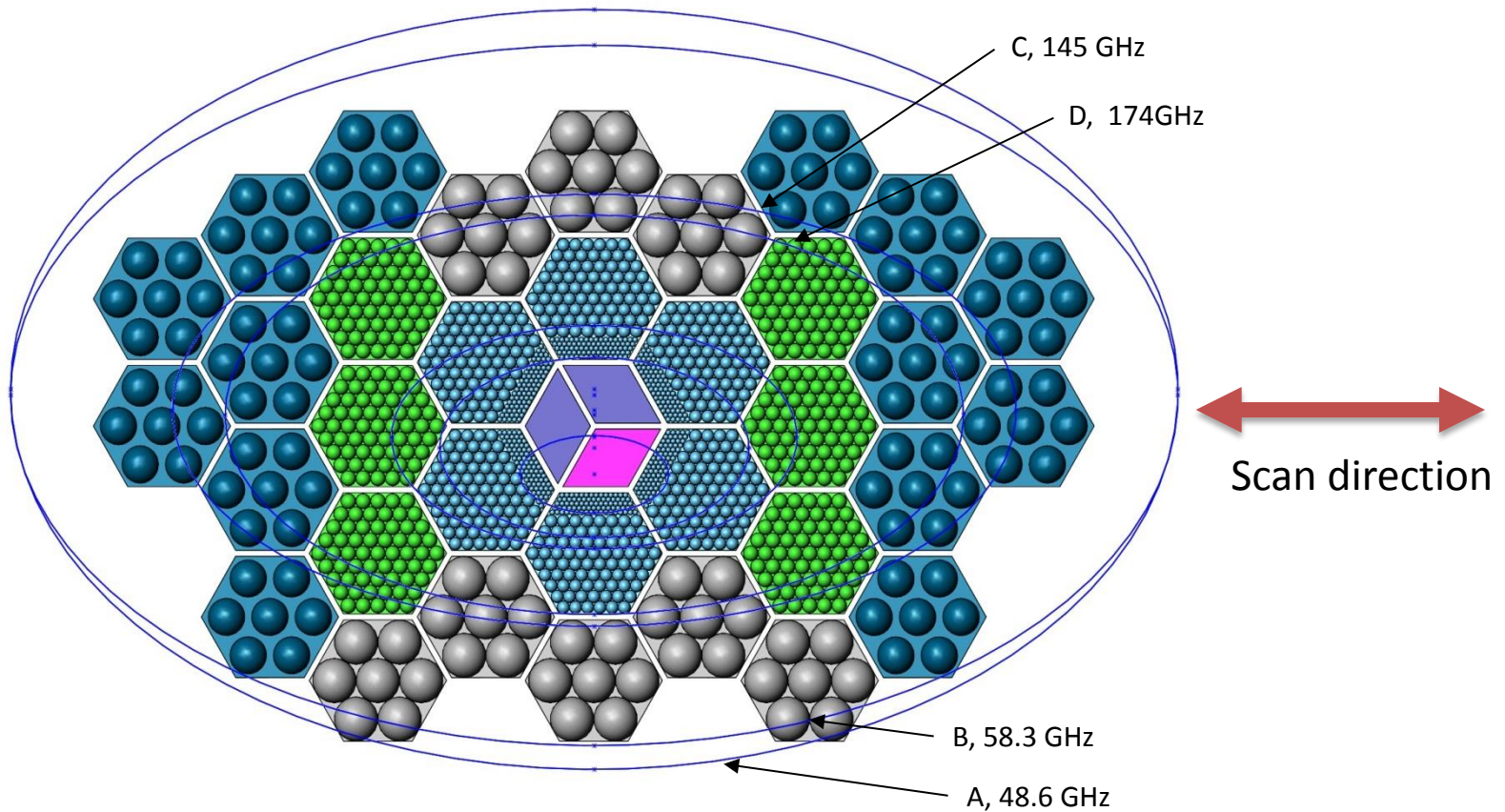
# Focal Plane V5

- Central wafer split, due to different technology types
  - Fewer F pixels, more G,H,I pixels
- approximately 19 x 12 deg, 65 x 45 cm.



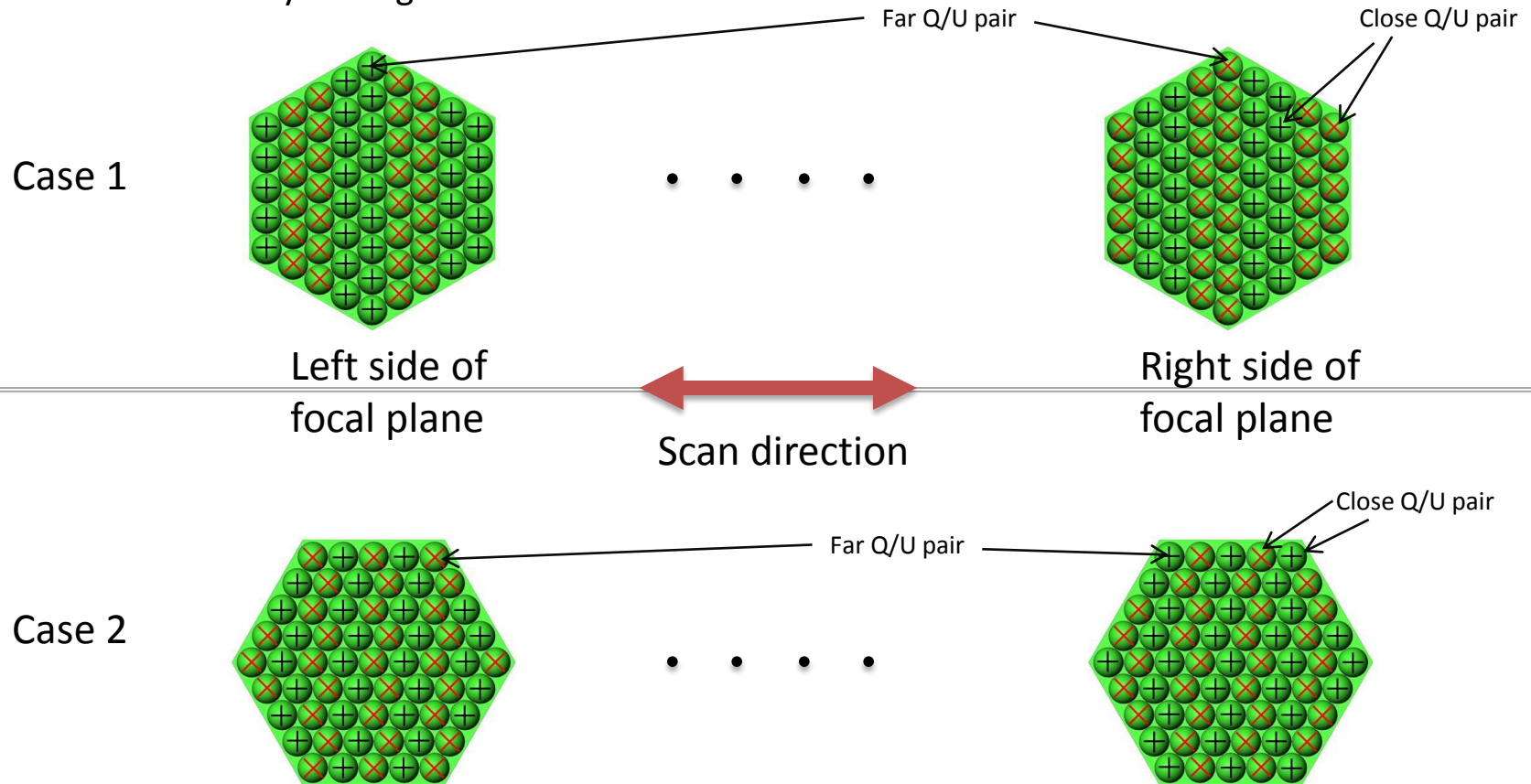
# Focal Plane rotated

- Rotated by 30 deg to put rows along scan direction.
- Nearly same pixel numbers ( -2 dark blue pixels, -4 gray pixels)
- approximately 20 x 11.5 deg, 69 x 43 cm.



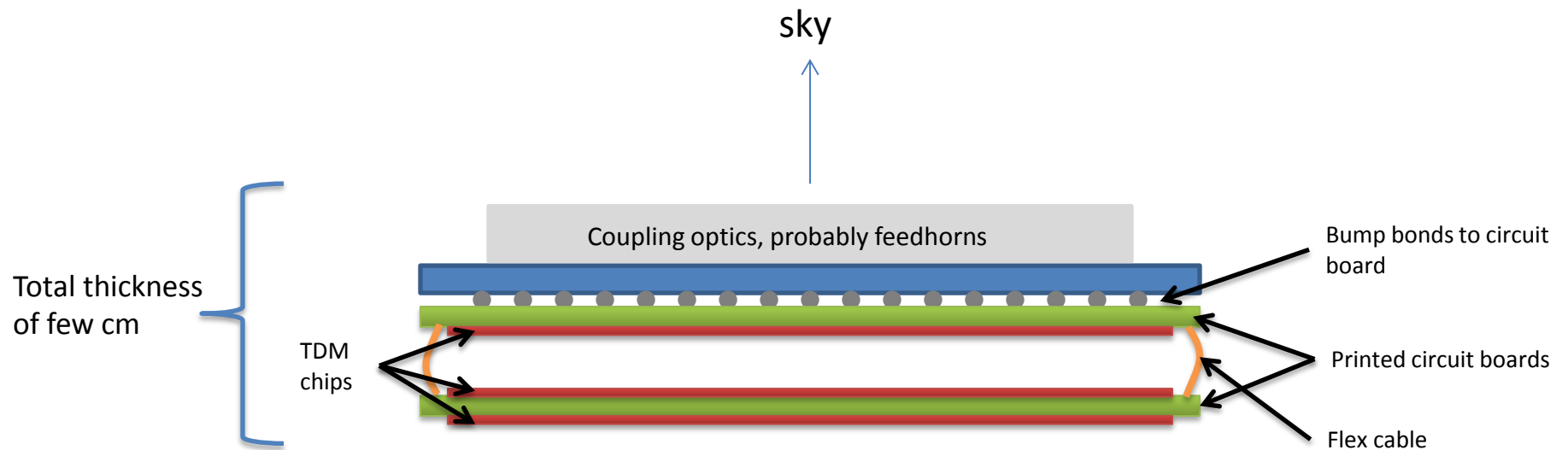
# Orienting Q/U pixels

- Q/U pixel pairs should follow each other along scan path.
- This is 0<sup>th</sup> order. Not account for distortion by the optics.
- Showing only a single wafer pair, but all pairs would be similar.
- Case 1 is original layout
- Case 2 is rotated by 30 deg.



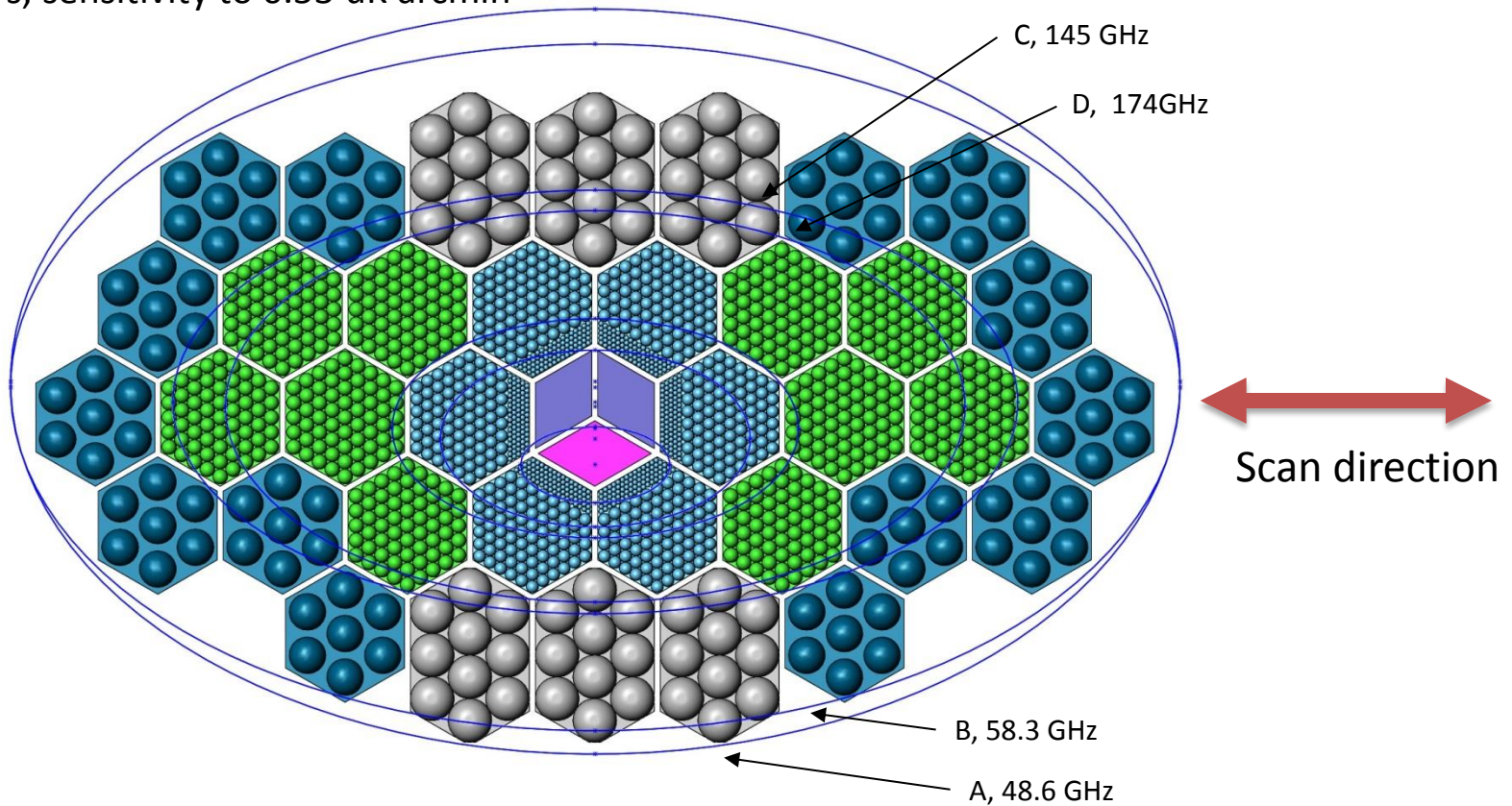
# Readout for central wafers

- More TDM chips at 100 mK are needed than fit in the area behind 1 detector wafer
- We need bump bonds on the back of a wafer to connect the number of bolos to readout



# Focal Plane, added 4 wafers

- 4 wafers added
- approximately 22.5 x 12 deg, 77 x 45 cm.
- Mirrors need to be larger in X dimension.
- Sensitivity was 0.61 uK arcmin
- If 4 'C' wafers, sensitivity to 0.56 uK arcmin
- If 4 'D' wafers, sensitivity to 0.53 uK arcmin



Selection of last week's slides on following pages  
for reference

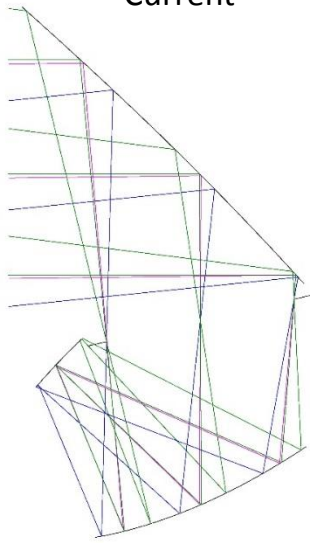
# Focal Plane V5

- Wire bonding or bump bonding chips on focal plane?
  - Wire bonds have heritage and allow more flexibility.
    - Limited to 1400 detectors per wafer 1700 detectors per hex wafer (bond pitch = 80  $\mu\text{m}$ )
  - Bump bonds allow more density of connections per chip.
  - If KIDs (or similar) are dominate tech in 5 years this point is moot.
- Volume needed for 100 mK readout components? 4K readout components?
  - 100 mK TDM requires 4  $\text{mm}^2$  per channel (Hannes)
  - 100 mK FDM requires LCs, about 50-80  $\text{mm}^2$  channel (from EBEX-IDS, LCs on silicon wafer)
  - 4K, both need SQUIDs

Pixel	Bands (GHz)	Upper edge of upper band (GHz)	V4 Number	V5 Number	Bolometers per wafer	Area behind 1 wafer ( $\text{mm}^2$ )	Area needed for TDM chips ( $\text{mm}^2$ )
A	21, 30, 43	48.6	60	60	60	8100	240
B	25, 36, 52	58.3	100	100	60	8100	240
C	62, 90, 129	145	366	366	366	5700	1500
D	75, 108, 155	174	510	510	990	5700	3960
E	186, 268, 385	433	480	480			
F	223, 321, 462	520	550	450	1350	1730	5400
G	555	624	200	220	1000	1730	4000
H	666	749	160	200			
I	799	899	120	180			

# Mirror limits to focal plane size

Current



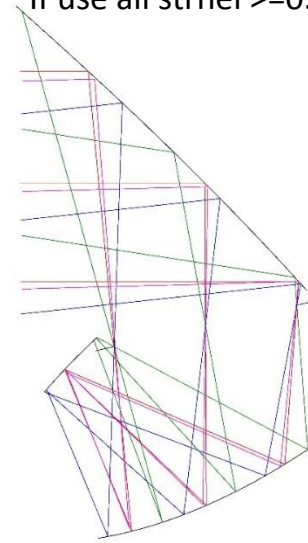
62.50 CM

best\_zrn.len

Scale: 0.04

07-Feb-18

If use all strhel  $\geq 0.8$



64.10 CM

best\_zrn.len

Scale: 0.04

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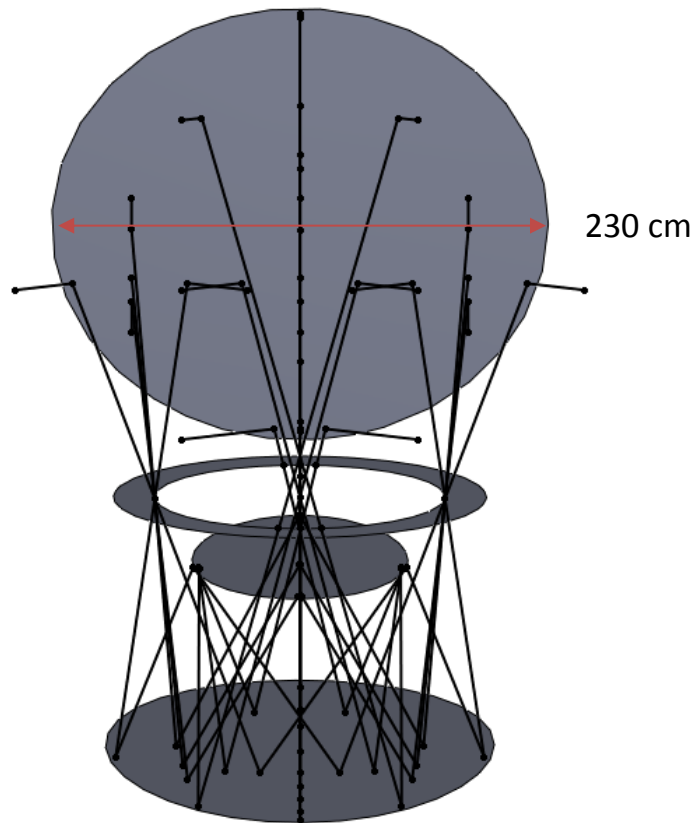
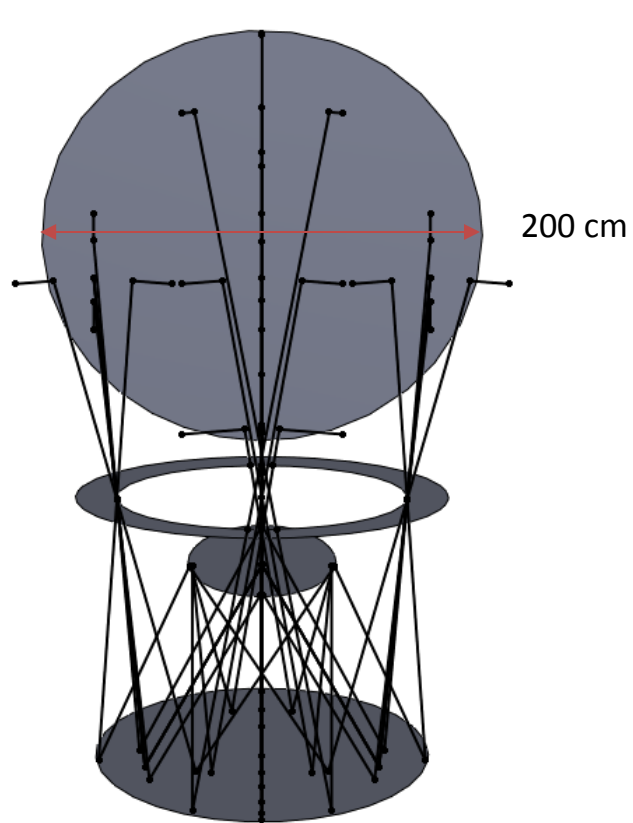
FOV	cm	deg
X	32.25	8.8
-X	-32.25	-8.8
Y	18.85	5.7
-Y	-25.65	7.0

X: in & out  
Y: on the page

FOV	cm	deg
X	46.9	12.9
-X	-46.9	-12.9
Y	20	6.1
-Y	-31.8	-8.6

Clearance to stop = 8.5 cm

Clearance to stop = 0 cm; as we go to -Y, clearance smaller



	Current	If use all Strehl $\geq 0.8$
Primary Mirror	270 cm X 200 cm	285 cm X 230 cm
Secondary Mirror	152 cm X 158 cm	178 cm X 168 cm
Focal Plane	65 cm X 45 cm	100 cm X 54 cm